

Product Summary

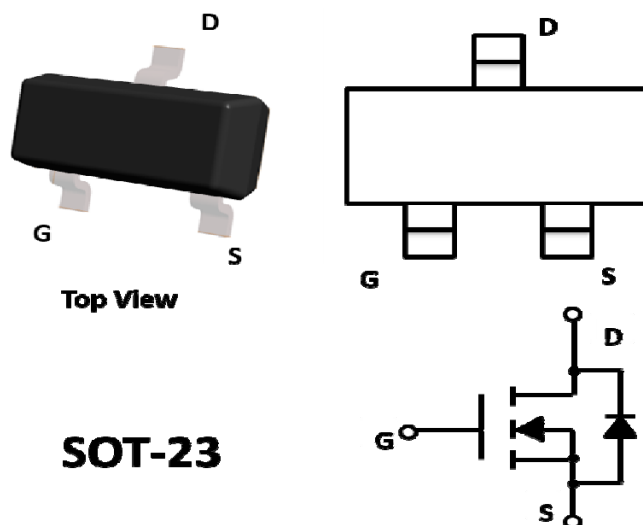
- V_{DS} 20V
- I_D 3.0A
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) <47 mohm
- $R_{DS(ON)}$ (at $V_{GS}=2.5V$) <65 mohm

General Description

- Trench Power LV MOSFET technology
- High Power and current handing capability

Applications

- PWM application
- Load switch



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	20	V
Gate-source Voltage	V_{GS}	± 10	V
Drain Current	I_D	$T_A=25^\circ\text{C}$ @ Steady State	3.0
		$T_A=70^\circ\text{C}$ @ Steady State	2.4
Pulsed Drain Current ^A	I_{DM}	14	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$	P_D	0.7	W
Thermal Resistance Junction-to-Ambient @ Steady State ^B	$R_{\theta JA}$	178	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ\text{C}$

Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
JH2302B	F2	2302B	3000	30000	120000	7"reel

JH2302B

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V, T_C=25^\circ\text{C}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.85	1.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=3.0A$		38	47	m Ω
		$V_{GS}=2.5V, I_D=3A$		52	65	
Diode Forward Voltage	V_{SD}	$I_S=3.0A, V_{GS}=0V$			1.2	V
Maximum Body-Diode Continuous Current	I_S				3.0	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V, f=1\text{MHz}$		260		pF
Output Capacitance	C_{oss}			44		
Reverse Transfer Capacitance	C_{rss}			29		
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=4.5V, V_{DS}=10V, I_D=4.3A$		3.8		nC
Gate Source Charge	Q_{gs}			0.65		
Gate Drain Charge	Q_{gd}			0.8		
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=4.5V, V_{DD}=10V, R_L=1.5\Omega, R_{GEN}=3\Omega$		13		ns
Turn-on Rise Time	t_r			54		
Turn-off Delay Time	$t_{D(off)}$			18		
Turn-off Fall Time	t_f			11		

A. Pulse Test: Pulse Width $\leq 300\mu s$, Duty cycle $\leq 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Typical Performance Characteristics

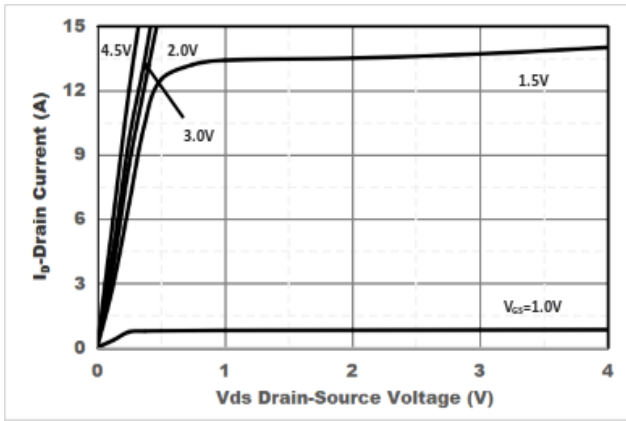


Figure1. Output Characteristics

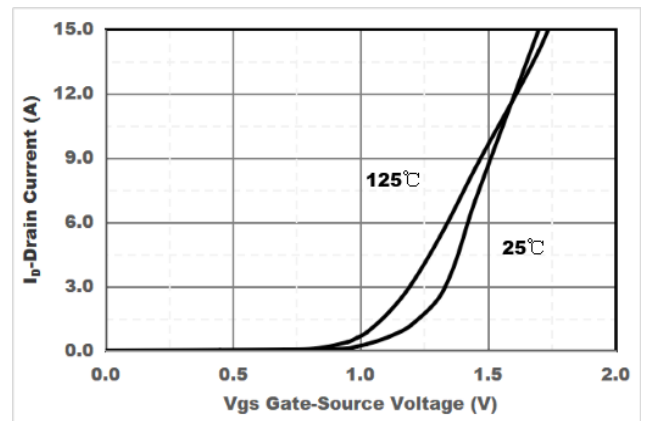


Figure2. Transfer Characteristics

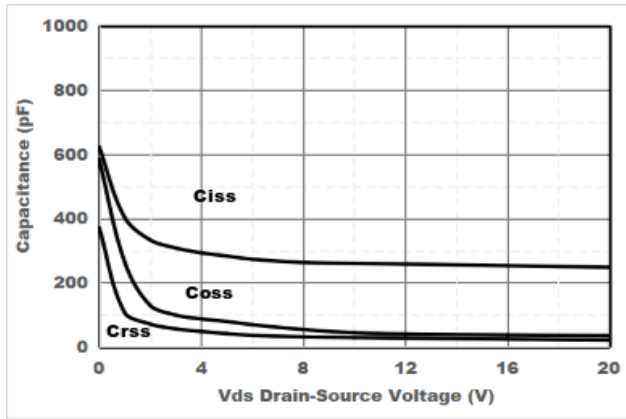


Figure3. Capacitance Characteristics

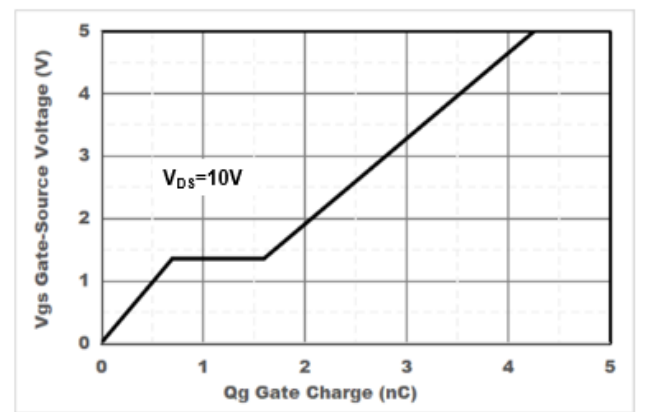


Figure4. Gate Charge

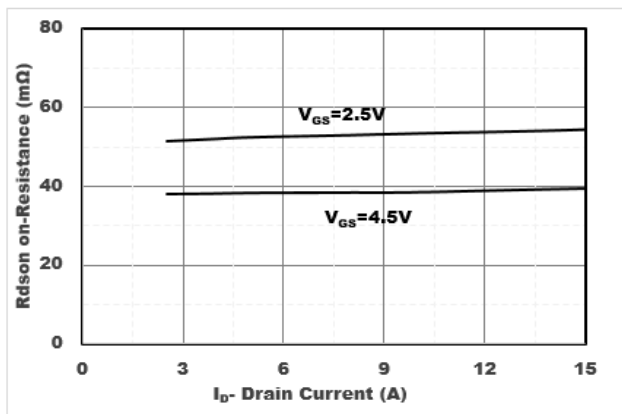


Figure5. Drain-Source on Resistance

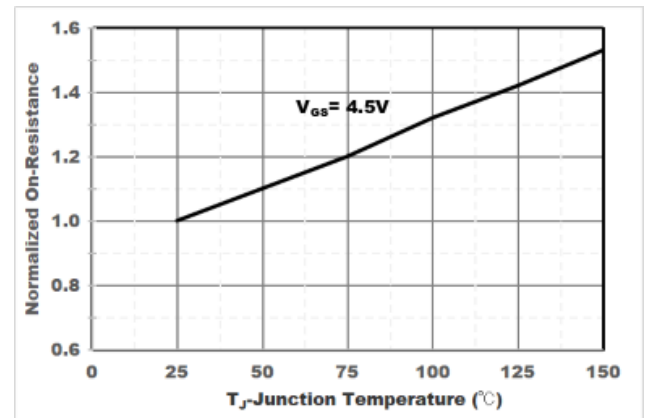


Figure6. Drain-Source on Resistance

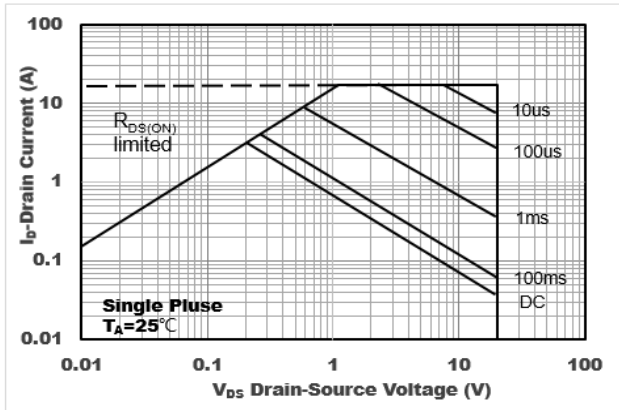


Figure7. Safe Operation Area

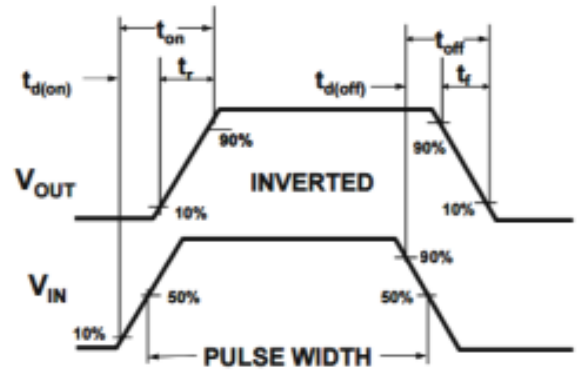
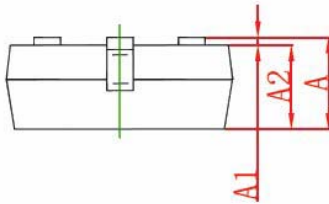
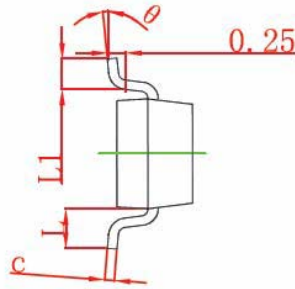
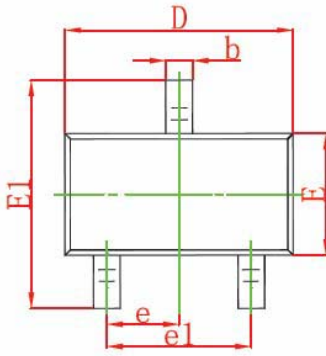


Figure8. Switching wave

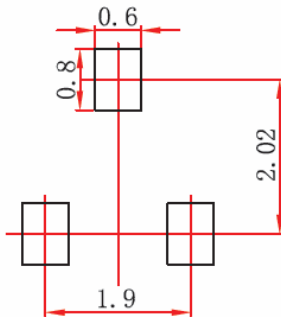
JH2302B

SOT-23 Package information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.